



אוניברסיטת בן-גוריון בנגב
Ben-Gurion University
of the Negev

Nano-Fabrication
Center

Wire Bonder

West bond 7476E



Description

An ultrasonic/thermosonic wedge-wedge wire bonder designed to interconnect wire leads to semi-conductor, hybrid or microwave devices.

Principle of operation

Bonds are made by the wedge-wedge technique using ultrasonic energy to attach wire at room temperature. The bonding tool is guided manually by the operator using hand/eye reference to bond targets and elevations.

Specifications / Capabilities

Bonds aluminum or gold wires.

17, 25 and 75 μ wires (0.7, 1 and 3 mil).

Materials

Aluminum or gold wires.

Link

<http://www.westbond.com/index.htm>

<http://www.westbond.com/7400espc.htm>